

LNJ115W85RA1

Hight Bright Surface Mounting Chip LED

TSS-2 Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

• Blue

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	65	mW
Forward current	I_F	15	mA
Pulse forward current *	I_{FP}	55	mA
Reverse voltage	V_R	5	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.**■ Lighting Color**

• Blue

• Red

• Red

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.**■ Electro-Optical Characteristics** $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

• Blue

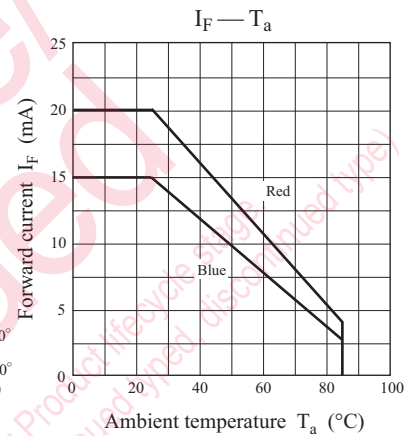
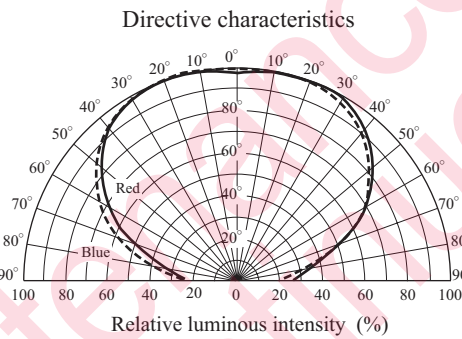
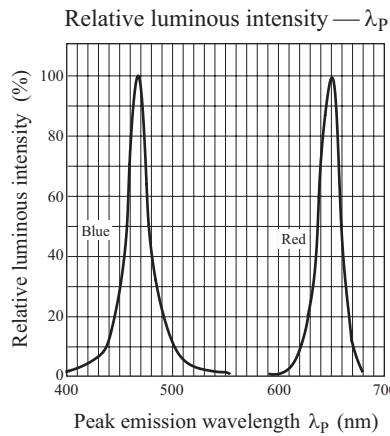
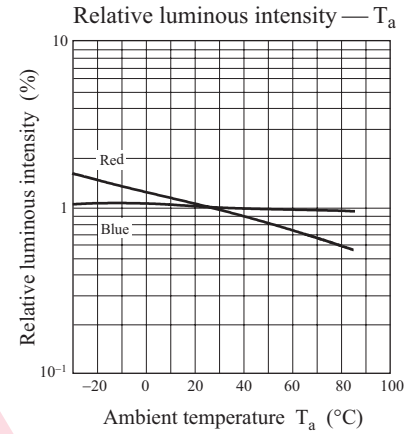
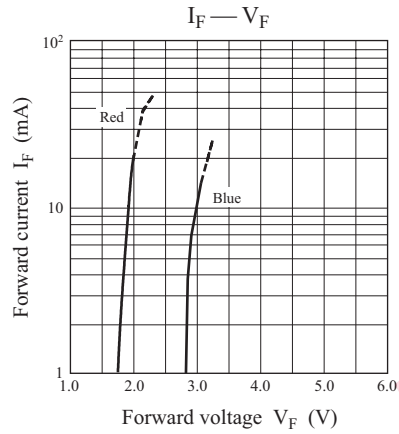
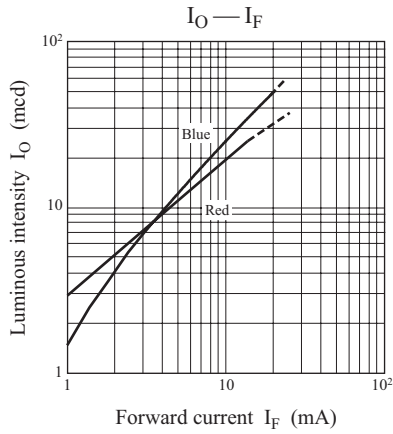
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O	$I_F = 5\text{ mA}$	5.0	12.0	41.8	mcd
Reverse current	I_R	$V_R = 5\text{ V}$			100	μA
Forward voltage	V_F	$I_F = 5\text{ mA}$		2.90	3.20	V
Peak emission wavelength	λ_p	$I_F = 5\text{ mA}$		465		nm
Dominant emission wavelength	λ_d	$I_F = 5\text{ mA}$	462	470	478	nm
Spectral half band width	$\Delta\lambda$	$I_F = 5\text{ mA}$		20		nm

Note) *: Measurement tolerance: $\pm 20\%$

• Red

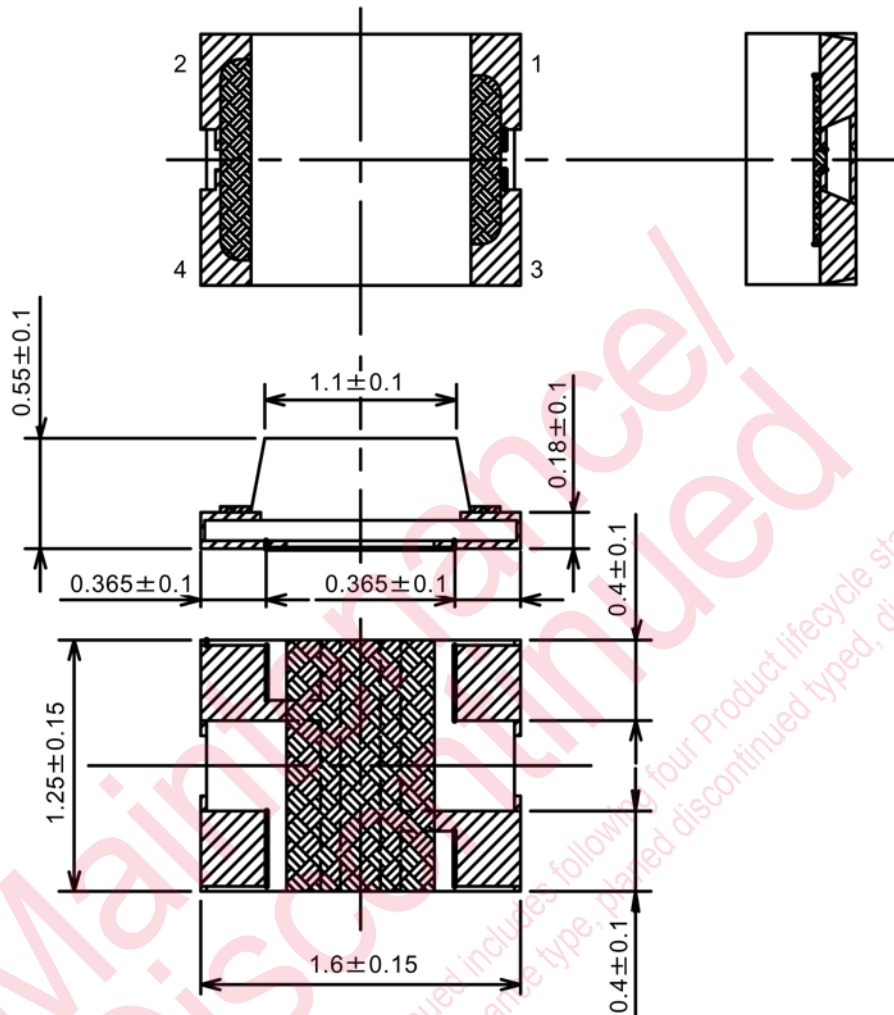
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O	$I_F = 10\text{ mA}$	12.0	24.0	60.8	mcd
Reverse current	I_R	$V_R = 4\text{ V}$			100	μA
Forward voltage	V_F	$I_F = 10\text{ mA}$		1.92	2.50	V
Peak emission wavelength	λ_p	$I_F = 10\text{ mA}$		645		nm
Dominant emission wavelength	λ_d	$I_F = 10\text{ mA}$	620	630	640	nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		22		nm

Note) *: Measurement tolerance: $\pm 20\%$



■ Package (Unit: mm)

KLTFTN4K1540



- Pin name
- 1, 3: Anode
- 2, 4: Cathode

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